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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/707,683	01/05/2004	Kai-Chi Chen	11846-US-PA	1682
31561	7590	08/14/2006	EXAMINER	
JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE 7 FLOOR-1, NO. 100 ROOSEVELT ROAD, SECTION 2 TAIPEI, 100 TAIWAN			ZARNEKE, DAVID A	
			ART UNIT	PAPER NUMBER
			2891	
DATE MAILED: 08/14/2006				

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No.	Applicant(s)
	10/707,683	CHEN ET AL.
	Examiner	Art Unit
	David A. Zarneke	2891

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) Responsive to communication(s) filed on _____.
- 2a) This action is **FINAL**. 2b) This action is non-final.
- 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) Claim(s) 1-5 is/are pending in the application.
 - 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) Claim(s) _____ is/are allowed.
- 6) Claim(s) 1-5 is/are rejected.
- 7) Claim(s) _____ is/are objected to.
- 8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) The specification is objected to by the Examiner.
- 10) The drawing(s) filed on _____ is/are: a) accepted or b) objected to by the Examiner.

Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
 - a) All b) Some * c) None of:
 1. Certified copies of the priority documents have been received.
 2. Certified copies of the priority documents have been received in Application No. _____.
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)	4) <input type="checkbox"/> Interview Summary (PTO-413)
2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)	Paper No(s)/Mail Date. _____.
3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date _____.	5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152)
	6) <input type="checkbox"/> Other: _____.

DETAILED ACTION

Reopening Prosecution

Prosecution on the merits of this application is reopened on claims 1-5, considered unpatentable for the reasons indicated in the rejection below.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1, 3, and 5 are rejected under 35 U.S.C. 102(b) as being anticipated by Venkateshwaran et al., US Patent 6,339,254.

Venkateshwaran (figure 4) teaches a chip package structure, comprising:

a carrier [610];

a chip [402], having an active surface with a plurality of bumps [412] thereon,

wherein the active surface of the chip is bonded to the carrier using a flip-chip bonding technique so that the chip and the carrier are electrically connected; and

an encapsulating material layer [410], covering the chip and the carrier and filling the bonding gap between the chip and the carrier, wherein the encapsulating material layer between the chip and the carrier has a first thickness and the encapsulating

material layer on the chip has a second thickness such that the second thickness is between 0.5 - 2 times the first thickness.

Regarding the thickness ratio, Venkateshwaran teaches the bumps [412] are 0.05-0.25 mm in diameter (4, 19-21), and that the bumps [411] are 0.25-0.5 mm in diameter (4, 26-27). Further, it is taught that the chip [402] is about 0.15-0.5 mm thick (5, 6-8). Therefore, in relation to the present claims, the first thickness is the same as the diameter of the bumps [412] and the second thickness is the difference between the diameter of the bumps [411] and the thickness of the chip [402]. Consequently, the second thickness is 0.10-0.45 mm when you subtract the minimum chip thickness (0.15 mm) from the diameter of the bumps [411]. This makes the ratio B= 0.10-0.45 and A=0.05-0.25, which clearly will significantly overlap with the claimed limitation of the second thickness is between 0.5 - 2 times the first thickness. For example, if B=0.10 and A=0.05, then the ratio is 2.

With respect to claim 3, Venkateshwaran (figure 6A) teaches the package further comprises an array of solder balls [611] attached to a surface of the carrier away from the chip.

As to claim 5, Venkateshwaran teaches the carrier is selected from a group consisting of a package substrate [400] and a lead frame (3, 60-62).

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

The factual inquiries set forth in *Graham v. John Deere Co.*, 383 U.S. 1, 148 USPQ 459 (1966), that are applied for establishing a background for determining obviousness under 35 U.S.C. 103(a) are summarized as follows:

1. Determining the scope and contents of the prior art.
2. Ascertaining the differences between the prior art and the claims at issue.
3. Resolving the level of ordinary skill in the pertinent art.
4. Considering objective evidence present in the application indicating obviousness or nonobviousness.

This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).

Claims 2 and 4 are rejected under 35 U.S.C. 103(a) as being unpatentable over Venkateshwaran et al., US Patent 6,339,254, as applied to claim 1 above.

Regarding claim 2, while Venkateshwaran fails to teach the maximum diameter of particles constituting the encapsulating material layer is smaller than 0.5 times the first thickness, it would have been obvious to one ordinary skill in the art at the time of

the invention to optimize the maximum particle diameter in order to allow easier flow of the material between the chip and the carrier (MPEP 2144.05).

With respect to claim 4, while Venkateshwaran fails to teach the package further comprises a passive component attached and electrically to the carrier, the attachment of a passive component to the carrier is common and well known to a skilled artisan and an obvious matter of design choice. One would do this in order to save space because placement of the passive component on the carrier allows for making smaller packages. Design choices and changes of size are generally recognized as being within the level of ordinary skill in the art (MPEP 2144.04(I), (IVA) & (IVB)).

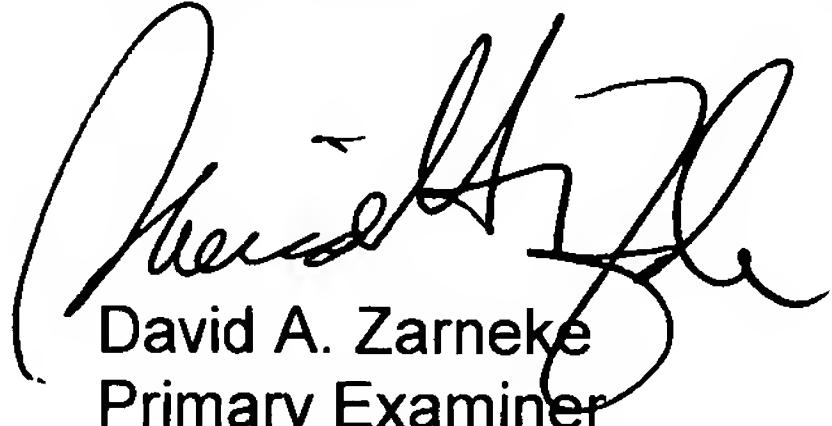
Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to David A. Zarneke whose telephone number is (571)-272-1937. The examiner can normally be reached on M-Th 7:30 AM-6 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, William Baumeister can be reached on (571)-272-1722. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only.

For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.



David A. Zarneke
Primary Examiner
July 11, 2006



B. WILLIAM BAUMEISTER
SUPERVISORY PATENT EXAMINER